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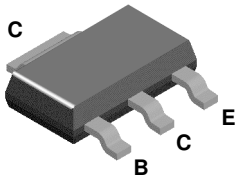
FAIRCHILD
SEMICONDUCTOR TM

TN6729A

NZT6729

TO-226



SOT-223

PNP General Purpose Amplifier

This device is designed for general purpose medium power amplifiers and switches requiring collector currents to 800 mA. Sourced from Process 79.

Absolute Maximum Ratings*

TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V_{CEO}	Collector-Emitter Voltage	80	V
V_{CBO}	Collector-Base Voltage	80	V
V_{EBO}	Emitter-Base Voltage	5.0	V
I_C	Collector Current - Continuous	1.0	A
T_J, T_{stg}	Operating and Storage Junction Temperature Range	-55 to +150	°C

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:
1) These ratings are based on a maximum junction temperature of 150 degrees C.
2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.
3) All voltages (V) and currents (A) are negative polarity for PNP transistors.

Thermal Characteristics

TA = 25°C unless otherwise noted

Symbol	Characteristic	Max		Units
		TN6729A	*NZT6729	
P_D	Total Device Dissipation Derate above 25°C	1.0 8.0	1.0 8.0	W mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	50		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	125	125	°C/W

*Device mounted on FR-4 PCB 36 mm X 18 mm X 1.5 mm; mounting pad for the collector lead min. 6 cm^2.

PNP General Purpose Amplifier
(continued)

Electrical Characteristics
TA = 25°C unless otherwise noted

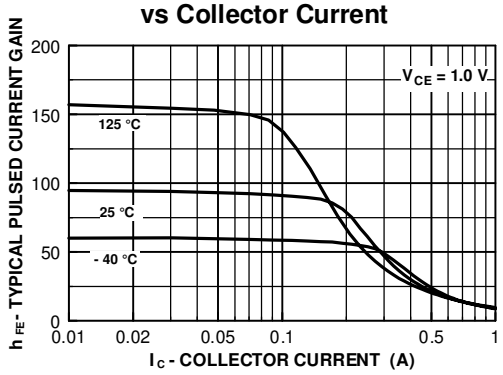
Symbol	Parameter	Test Conditions	Min	Max	Units
OFF CHARACTERISTICS					
$V_{(BR)CEO}$	Collector-Emitter Breakdown Voltage	I_C = 1.0 mA, I_B = 0	80		V
$V_{(BR)CBO}$	Collector-Base Breakdown Voltage	I_C = 100 μA, I_E = 0	80		V
$V_{(BR)EBO}$	Emitter-Base Breakdown Voltage	I_E = 1.0 mA, I_C = 0	5.0		V
I_{CBO}	Collector-Cutoff Current	V_{CB} = 60 V, I_E = 0		0.1	μA
I_{EBO}	Emitter-Cutoff Current	V_{EB} = 5.0 V, I_C = 0		10	μA
ON CHARACTERISTICS*					
h_{FE}	DC Current Gain	I_C = 50 mA, V_{CE} = 1.0 V I_C = 250 mA, V_{CE} = 1.0 V I_C = 500 mA, V_{CE} = 1.0 V	80 50 20	 250 	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	I_C = 250 mA, I_B = 10 mA I_C = 250 mA, I_B = 25 mA		0.5 0.35	V V
$V_{BE(on)}$	Base-Emitter On Voltage	I_C = 250 mA, V_{CE} = 1.0 V		1.2	V
SMALL SIGNAL CHARACTERISTICS					
h_{fe}	Small-Signal Current Gain	I_C = 200 mA, V_{CE} = 5.0 V, f = 20 MHz	2.5	25	
C_{cb}	Collector-Base Capacitance	V_{CB} = 10 V, I_E = 0, f = 1.0 MHz		30	pF

*Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 1.0%

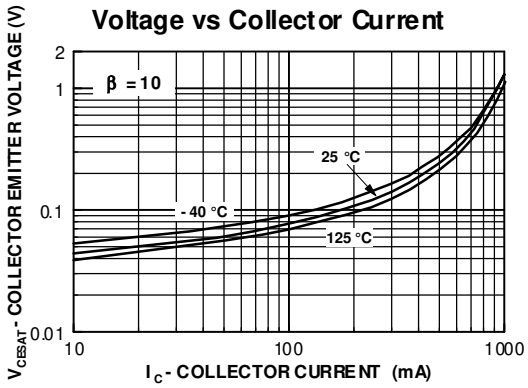
NOTE: All voltages (V) and currents (A) are negative polarity for PNP transistors.

Typical Characteristics

Typical Pulsed Current Gain vs Collector Current

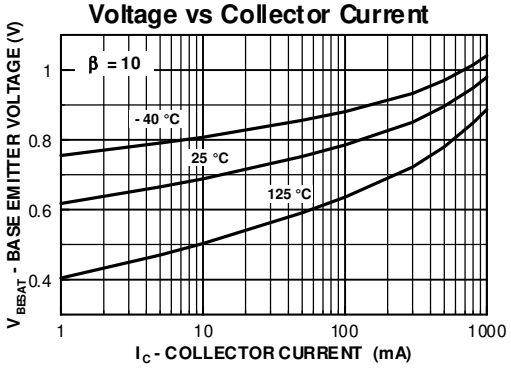


Collector-Emitter Saturation Voltage vs Collector Current

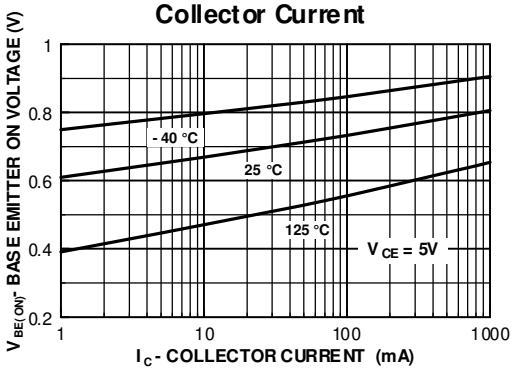


Typical Characteristics (continued)

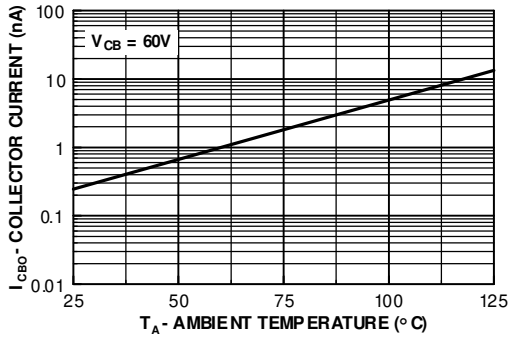
Base-Emitter Saturation Voltage vs Collector Current



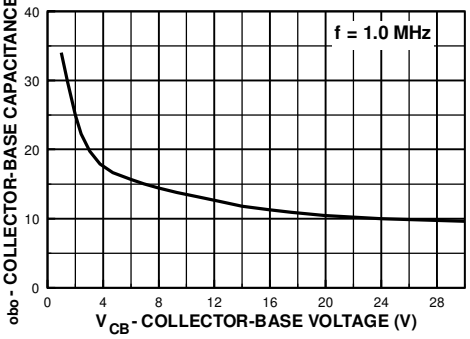
Base Emitter ON Voltage vs Collector Current



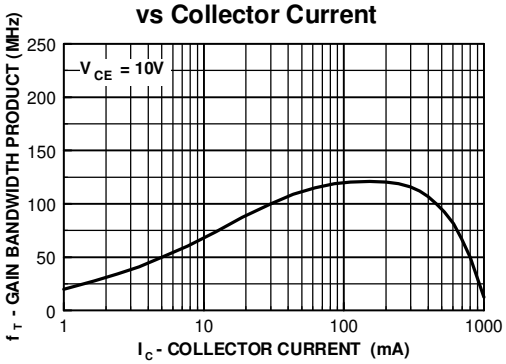
Collector-Cutoff Current vs Ambient Temperature



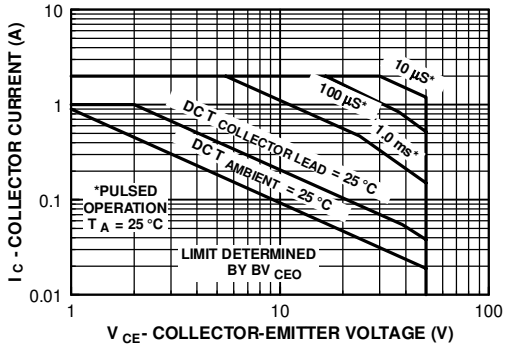
Collector-Base Capacitance vs Collector-Base Voltage



Gain Bandwidth Product vs Collector Current

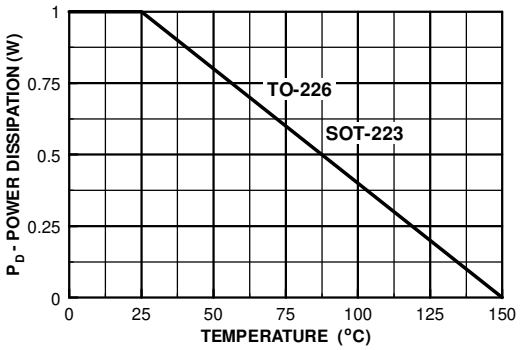


Safe Operating Area TO-226 / SOT-223



Typical Characteristics (continued)

Power Dissipation vs Ambient Temperature

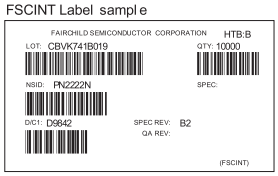


TO-226AE Tape and Reel Data

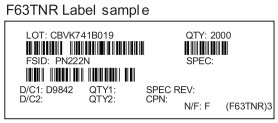
FAIRCHILD SEMICONDUCTOR™

TO-226AE Packaging
Configuration: Figure 1.0

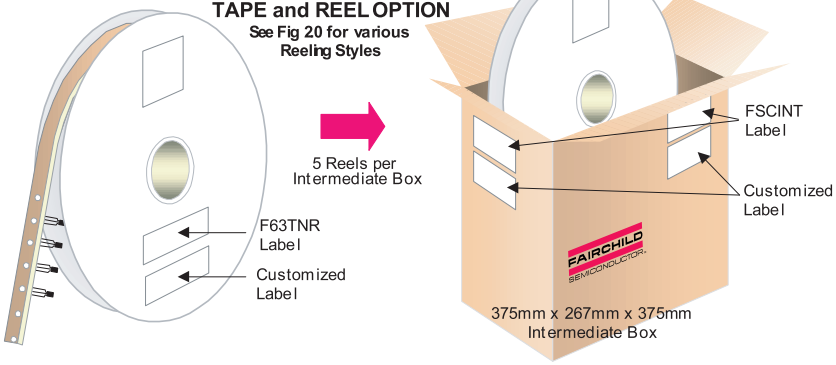
FSCINT Label sample



F63TNR Label sample



TAPE and REEL OPTION
See Fig 20 for various Reeling Styles

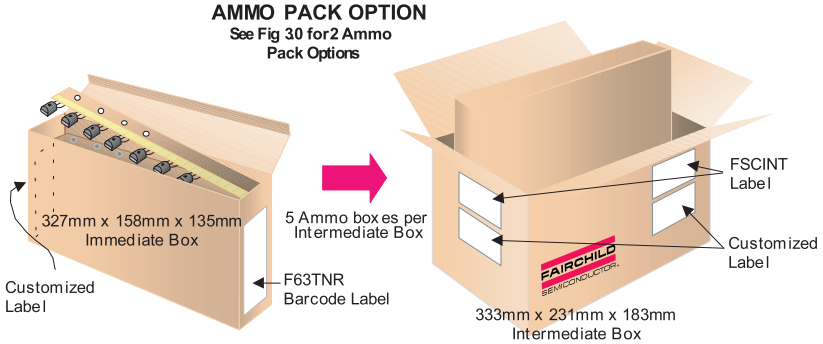


AMMO PACK OPTION
See Fig 30 for2 Ammo Pack Options

TO-226AE TNR/AMMO PACKING INFORMATION

Packing	Style	Quantity	EOL code
Reel	A	2,000	D26Z
	E	2,000	D27Z
Ammo	M	2,000	D74Z
	P	2,000	D75Z

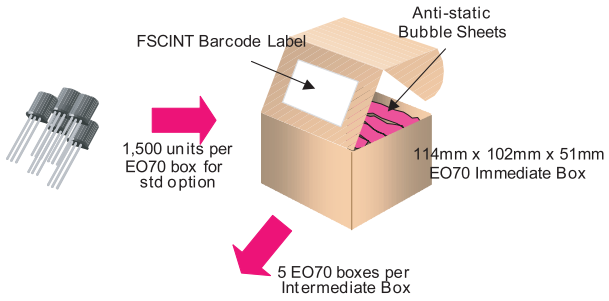
Unit weight = 0.300gm
Reel weight with components = 0.868 kg
Ammo weight with components = 0.880 kg
Max quantity per intermediate box = 10,000 units

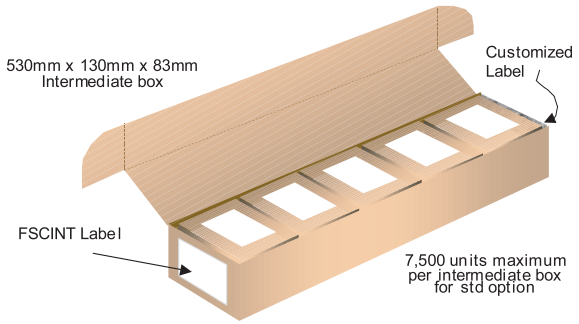


BULK OPTION
See Bulk Packing Information table

(TO-226AE) BULK PACKING INFORMATION

EOL CODE	DESCRIPTION	LEADCLIP DIMENSION	QUANTITY
J18Z	TO-18 OPTION STD	NO LEAD CLIP	1.0 K / BOX
J05Z	TO-5 OPTION STD	NO LEAD CLIP	1.0 K / BOX
NO EOL CODE	TO-226 STANDARD STRAIGHT	NO LEADCLIP	1.5 K / BOX

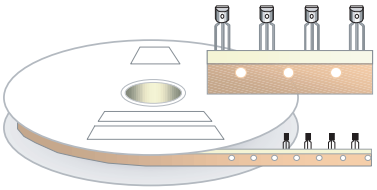




TO-226AE Tape and Reel Data, continued

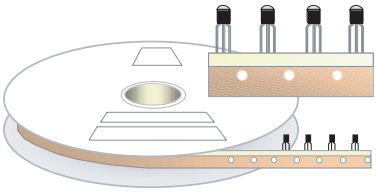
TO-226AE Reeling Style
Configuration: Figure 2.0

Machine Option "A" (H)



Style "A" D26Z, D70Z (s/h)

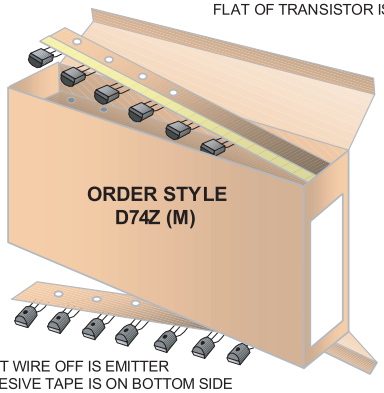
Machine Option "E" (J)



Style "E" D27Z, D71Z (s/h)

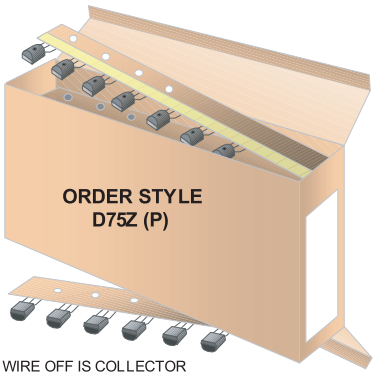
TO-226AE Radial Ammo Packaging
Configuration: Figure 3.0

FIRST WIRE OFF IS COLLECTOR (ON PKG. 92)
ADHESIVE TAPE IS ON THE TOP SIDE
FLAT OF TRANSISTOR IS ON TOP



FIRST WIRE OFF IS EMITTER
ADHESIVE TAPE IS ON BOTTOM SIDE
FLAT OF TRANSISTOR IS ON BOTTOM

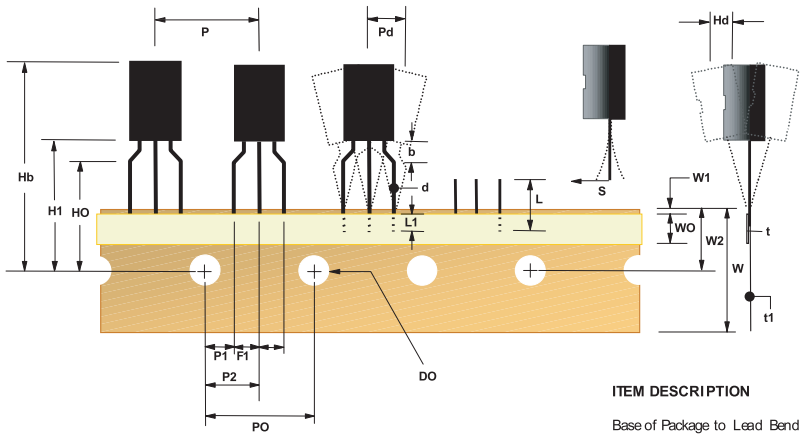
FIRST WIRE OFF IS EMITTER (ON PKG. 92)
ADHESIVE TAPE IS ON THE TOP SIDE
FLAT OF TRANSISTOR IS ON BOTTOM



FIRST WIRE OFF IS COLLECTOR
ADHESIVE TAPE IS ON BOTTOM SIDE
FLAT OF TRANSISTOR IS ON TOP

TO-226AE Tape and Reel Data, continued

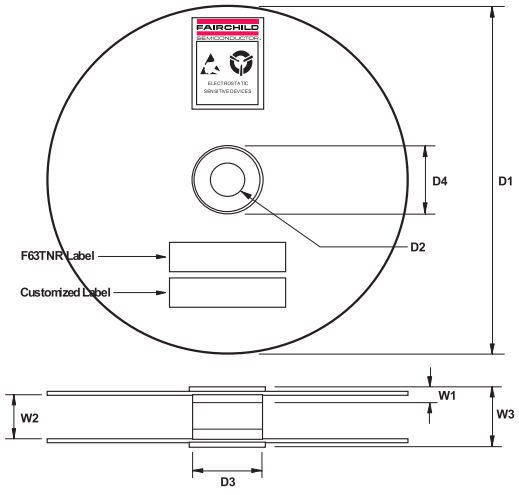
TO-226AE Tape and Reel Taping Dimension Configuration: Figure 4.0



ITEM DESCRIPTION	SYMBOL	DIMENSION
Base of Package to Lead Bend	b	0.098 (max)
Component Height	Hb	1.078 (+/- 0.050)
Lead Clinch Height	HO	0.630 (+/- 0.020)
Component Base Height	H1	0.748 (+/- 0.020)
Component Alignment (side/side)	Pd	0.040 (max)
Component Alignment (front/back)	Hd	0.031 (max)
Component Pitch	P	0.500 (+/- 0.020)
Feed Hole Pitch	PO	0.500 (+/- 0.008)
Hole Center to First Lead	P1	0.150 (+0.009, -0.010)
Hole Center to Component Center	P2	0.247 (+/- 0.007)
Lead Spread	F1/F2	0.104 (+/- 0.010)
Lead Thickness	d	0.018 (+0.002, -0.003)
Cut Lead Length	L	0.429 (max)
Taped Lead Length	L1	0.209 (+0.051, -0.052)
Taped Lead Thickness	t	0.032 (+/- 0.006)
Carrier Tape Thickness	t1	0.021 (+/- 0.006)
Carrier Tape Width	W	0.708 (+0.020, -0.019)
Hold-down Tape Width	WO	0.236 (+/- 0.012)
Hold-down Tape position	W1	0.035 (max)
Feed Hole Position	W2	0.360 (+/- 0.025)
Sprocket Hole Diameter	DO	0.157 (+0.008, -0.007)
Lead Spring Out	S	0.004 (max)

Note: All dimensions are in inches.

TO-226AE Reel Configuration: Figure 5.0



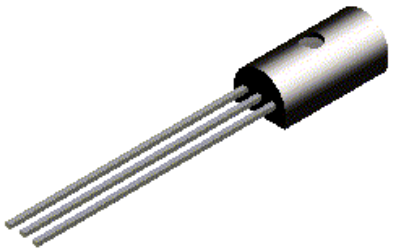
ITEM DESCRIPTION	SYMBOL	MINIMUM	MAXIMUM
Reel Diameter	D1	13.975	14.025
Arbor Hole Diameter (Standard)	D2	1.160	1.200
(Small Hole)	D2	0.650	0.700
Core Diameter	D3	3.100	3.300
Hub Recess Inner Diameter	D4	2.700	3.100
Hub Recess Depth	W1	0.370	0.570
Flange to Flange Inner Width	W2	1.630	1.690
Hub to Hub Center Width	W3		2.090

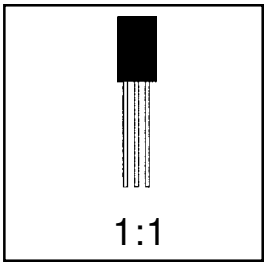
Note: All dimensions are inches

TO-226AE Package Dimensions

FAIRCHILD SEMICONDUCTOR™

TO-226AE (FS PKG Code 95, 99)

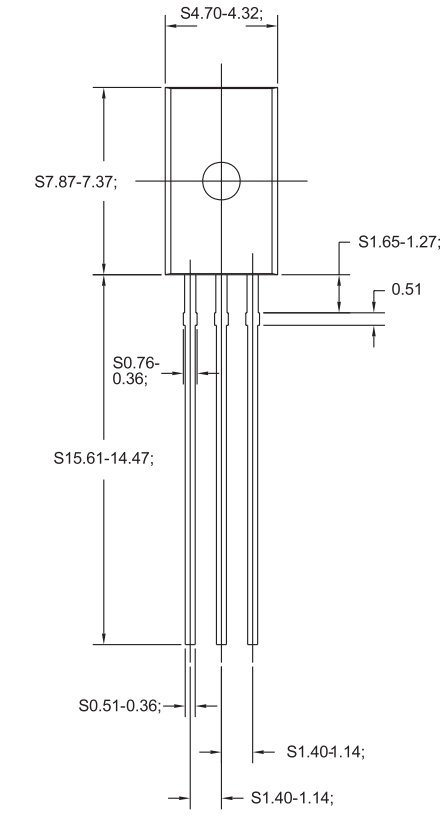


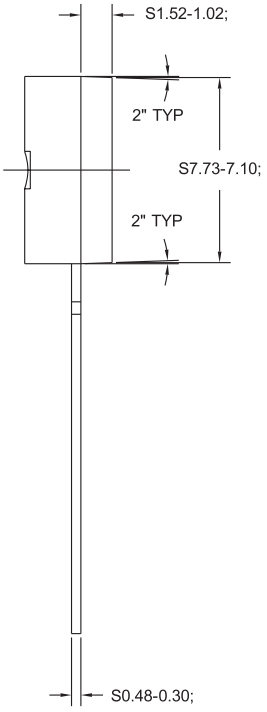


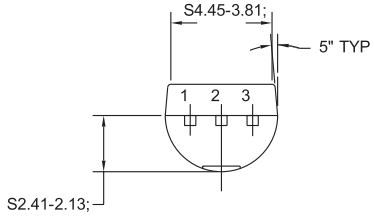
Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.300







PIN	99	95
1	E	E
2	B	C
3	C	B

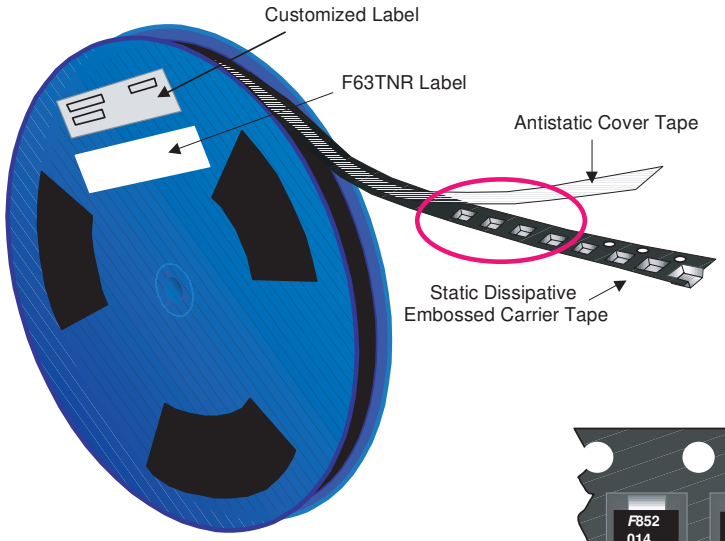
TO-226AE (95,99)

For leadformed option ordering,
refer to Tape & Reel data information.

SOT-223 Tape and Reel Data

FAIRCHILD SEMICONDUCTOR™

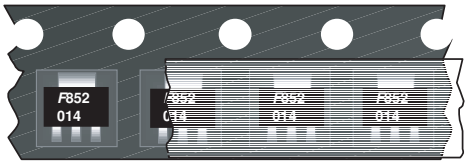
SOT-223 Packaging Configuration: Figure 1.0



Packaging Description:

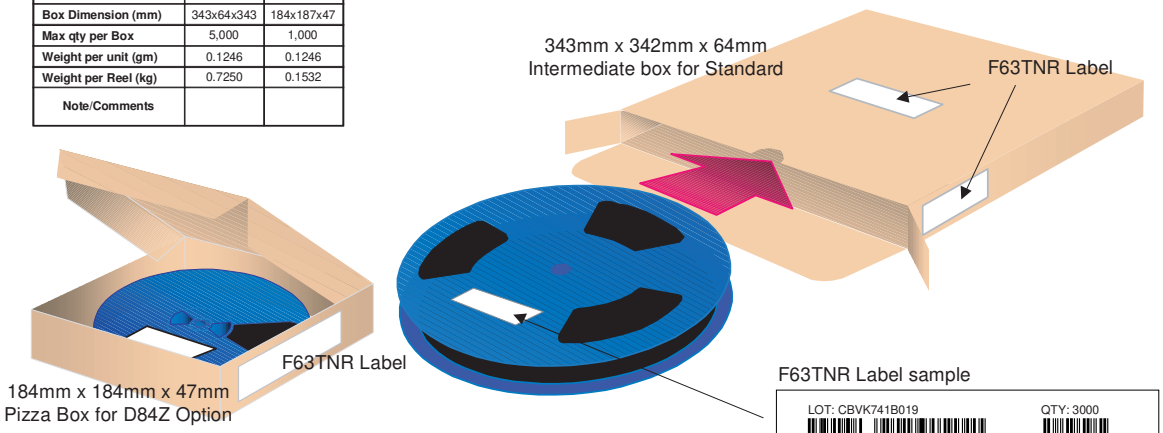
SOT-223 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 2,500 units per 13" or 330cm diameter reel. The reels are dark blue in color and is made of polystyrene plastic (anti-static coated). Other option comes in 500 units per 7" or 177cm diameter reel. This and some other options are further described in the Packaging Information table.

These full reels are individually barcode labeled and placed inside a standard intermediate box (illustrated in figure 1.0) made of recyclable corrugated brown paper. One box contains two reels maximum. And these boxes are placed inside a barcode labeled shipping box which comes in different sizes depending on the number of parts shipped.

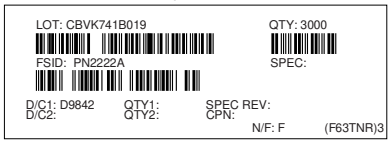


SOT-223 Unit Orientation

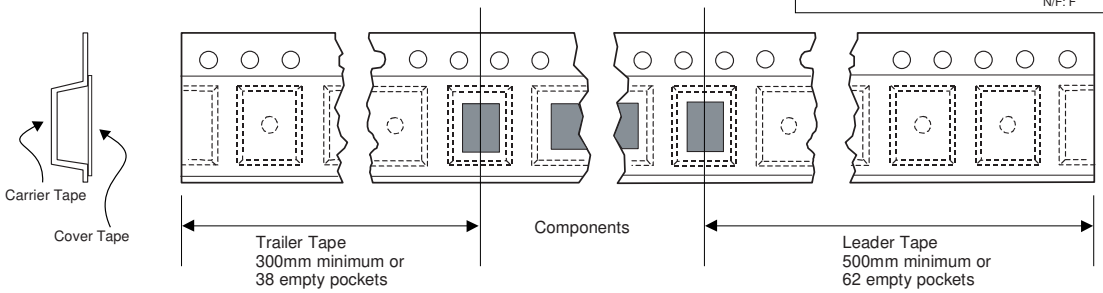
SOT-223 Packaging Information		
Packaging Option	Standard (no flow code)	D84Z
Packaging type	TNR	TNR
Qty per Reel/Tube/Bag	2,500	500
Reel Size	13" Dia	7" Dia
Box Dimension (mm)	343x64x343	184x187x47
Max qty per Box	5,000	1,000
Weight per unit (gm)	0.1246	0.1246
Weight per Reel (kg)	0.7250	0.1532
Note/Comments		



F63TNR Label sample

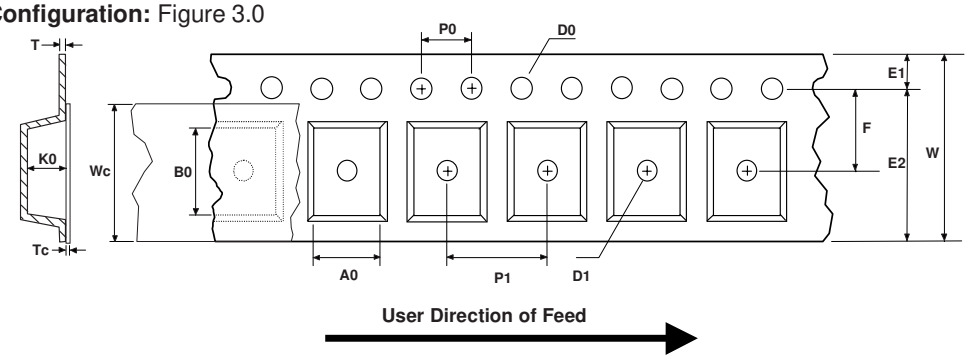


SOT-223 Tape Leader and Trailer Configuration: Figure 2.0



SOT-223 Tape and Reel Data, continued

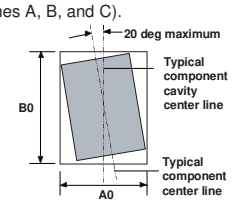
SOT-223 Embossed Carrier Tape
Configuration: Figure 3.0



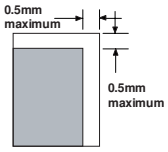
Dimensions are in millimeter														
Pkg type	**A0**	**B0**	**W**	**D0**	**D1**	**E1**	**E2**	**F**	**P1**	**P0**	**K0**	**T**	**Wc**	**Tc**
SOT-223 (12mm)	6.83 +/-0.10	7.42 +/-0.10	12.0 +/-0.3	1.55 +/-0.05	1.50 +/-0.10	1.75 +/-0.10	10.25 min	5.50 +/-0.05	8.0 +/-0.1	4.0 +/-0.1	1.88 +/-0.10	0.292 +/- 0.0130	9.5 +/-0.025	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).

Sketch A (Side or Front Sectional View)
Component Rotation

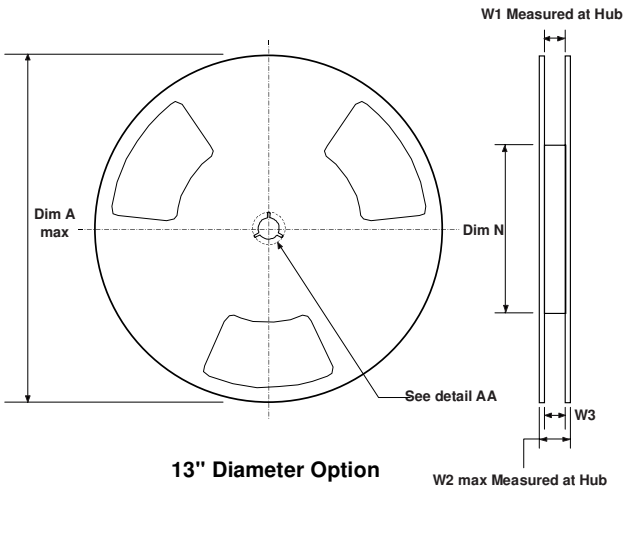


Sketch B (Top View)
Component Rotation

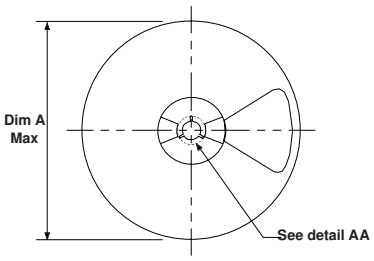


Sketch C (Top View)
Component lateral movement

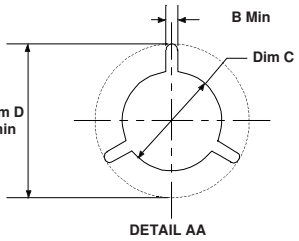
SOT-223 Reel Configuration: Figure 4.0



13" Diameter Option



7" Diameter Option

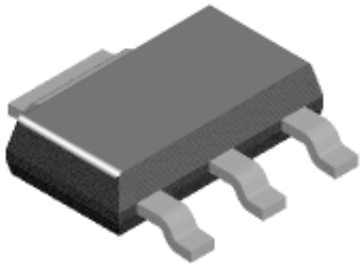


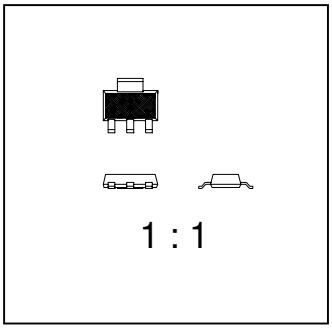
Dimensions are in inches and millimeters									
Tape Size	**Reel Option**	**Dim A**	**Dim B**	**Dim C**	**Dim D**	**Dim N**	**Dim W1**	**Dim W2**	**Dim W3 (LSL-USL)**
12mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	5.906 150	0.488 +0.078/-0.000 12.4 +2/0	0.724 18.4	0.469 – 0.606 11.9 – 15.4
12mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	7.00 178	0.488 +0.078/-0.000 12.4 +2/0	0.724 18.4	0.469 – 0.606 11.9 – 15.4

SOT-223 Package Dimensions

FAIRCHILD SEMICONDUCTOR™

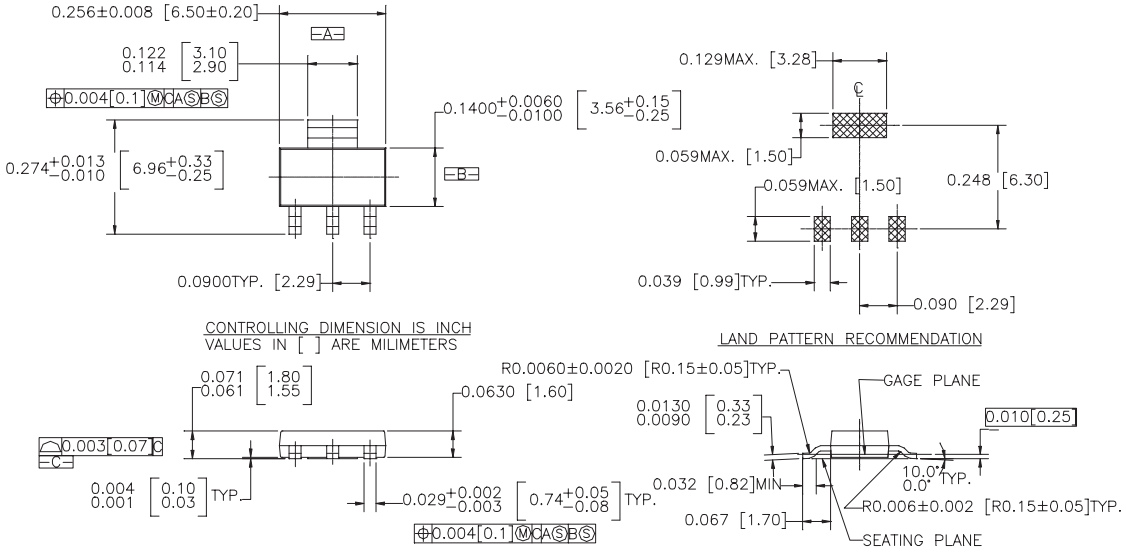
SOT-223 (FS PKG Code 47)





Scale 1:1 on letter size paper

Part Weight per unit (gram): 0.1246



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2. REFERENCE JEDEC REGISTRATION TO−261, VARIATION AA, ISSUE A, DATED JAN 1990

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